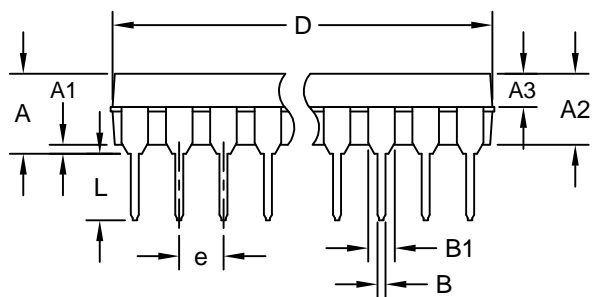
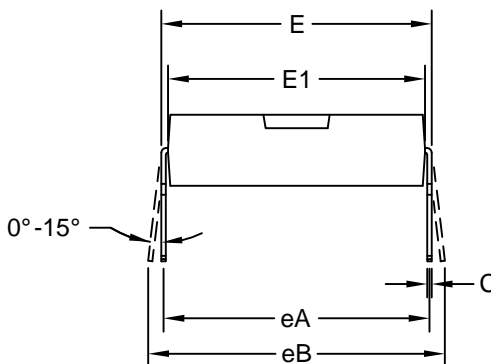


TOP VIEW



FRONT VIEW



SIDE VIEW

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	-	0.200	-	5.08
A1	0.015	-	0.39	-
A2	0.125	0.175	3.18	4.45
A3	0.055	0.080	1.40	2.03
B	0.016	0.020	0.41	0.51
B1	0.045	0.065	1.14	1.65
C	0.008	0.012	0.21	0.30
D1	0.005	0.009	0.13	0.22
E	0.600	0.625	15.24	15.87
E1	0.525	0.575	13.34	14.61
e	0.100 BSC		2.54 BSC	
eA	0.600 BSC		15.24 BSC	
eB	-	0.700	-	17.78
L	0.120	0.150	3.05	3.81

VARIATIONS:

DIM	INCHES		MILLIMETERS		N	MS011
	MIN	MAX	MIN	MAX		
D	1.230	1.270	31.24	32.26	24	AA
D	1.430	1.470	36.32	37.34	28	AB
D	2.025	2.075	51.44	52.71	40	AC

NOTES:

1. D&E DO NOT INCLUDE MOLD FLASH.
2. MOLD FLASH OR PROTRUSIONS NOT TO EXCEED 0.15mm (.006").
3. CONTROLLING DIMENSION: MILLIMETERS.
4. MEETS JEDEC MS011.
5. N = NUMBER OF PINS.

DALLAS SEMICONDUCTOR **MAXIM**

PROPRIETARY INFORMATION

TITLE:
PACKAGE OUTLINE, .600" PDIP

APPROVAL	DOCUMENT CONTROL NO. 21-0044	REV. B	1/1
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